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D. M. Matala
5/30/02
Pn. Amdt A
503.39144X00

THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): ITABASHI et al

Serial No.: 09/678,800

Filed: October 4, 2000

For: Electroless Copper Plating Machine Thereof, And Multi-Layer Printed Wiring Board

Group: 1741

Examiner:

PRELIMINARY AMENDMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

May 7, 2001

Sir:

The following preliminary amendments and remarks are respectfully submitted in connection with the above-identified application.

IN THE TITLE:

Please amend the title to read as follows:

Electroless Copper Plating Machine, And Multi-Layer Printed Wiring Board

IN THE SPECIFICATION:

Please replace the original specification with the attached Substitute Specification.

IN THE ABSTRACT OF THE DISCLOSURE:

Please replace the original abstract with the attached abstract.